

	3643	((thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas) and (gap groove dip recess\$4 space opening hole crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:35
	0	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas) and (gap groove dip recess\$4 space opening hole crack)) and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:31
	1	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas) and (gap groove dip recess\$4 space opening hole crack)) and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:31
	0	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas) and (gap groove dip recess\$4 space opening hole crack)) and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) near3 stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:34
	1964	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas) and (gap groove dip recess\$4 space opening hole crack)) and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) (bond\$4 adhere\$4 stick\$4) near3 stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:35
	2823	((thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas) and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) (bond\$4 adhere\$4 stick\$4) near3 stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:35
	0	((thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas) and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:36
	103	(wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:46
	10	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 stiction) and (thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:37
	10	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 stiction) and (thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:43
	2	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 stiction) and (thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) same gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:42
	36	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 stiction) and (thermal heat\$4) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:43

	11	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 stiction) and (thermal heat\$4) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) same gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:48
	1708	(wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 (stiction friction)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:48
	15	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 (stiction friction)) and (thermal heat\$4) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) same gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 15:30
	1	(wafer\$4 layer\$4 substrate\$4 film\$4) near3 stiction and (thermal heat\$4) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 temperature	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 15:32
	17	((wafer\$4 layer\$4 substrate\$4 film\$4) near3 stiction) and (test\$4 detect\$4 inspect\$4 measur\$4 sens\$4 gauge indicat\$4 estimat\$4 evaluat\$4 calculate\$4) near3 temperature same heat\$4	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 15:33
	207	(wafer\$4 layer\$4 substrate\$4 film\$4) near3 stiction	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 15:35